

**In the Drawings**

Please amend proposed Fig. 2 per the provided drawing sheet showing a hand-written correction in red ink.

**In the Claims**

(1). Please amend the claims as follows:

A3  
3. **(Once Amended)** An apparatus for manufacturing a semiconductor device, comprising:

an upper electrode; and

ju3  
a pressure detecting means provided inside said upper electrode that supplies gas to a parallel-plate dry etching apparatus.

4. **(Once Amended)** The apparatus according to claim 3, wherein said upper electrode comprises a cooling plate having a plurality of gas supply holes for supplying the gas; a gas-introducing plate having gas holes for introducing the gas onto a semiconductor wafer; and a jig for fixing said gas-introducing plate to said cooling plate, wherein said pressure detecting means is provided between said gas-introducing plate and said cooling plate.

Sub B4  
5. **(Once Amended)** An apparatus for manufacturing a semiconductor device, comprising:

an upper electrode;  
a first pressure detecting means provided inside of said first electrode that  
supplies gas in a parallel-plate dry etching apparatus; and  
a second pressure detecting means provided within said dry etching  
apparatus in which a wafer is placed.

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7. **(Once Amended)** The apparatus according to claim 5, wherein said upper electrode comprises a cooling plate having a plurality of gas supply holes for supplying the gas, a gas-introducing plate having gas holes for introducing the gas onto a semiconductor wafer, a jig for fixing said gas-introducing plate to said cooling plate, wherein said first pressure detecting means is provided between said gas-introducing plate and said cooling plate, and wherein said second pressure detecting means is provided within an etching chamber in which said wafer is placed.

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(2). Please add the following claims:

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8. **(Newly Added)** An apparatus according to claim 4, wherein said gas holes increase in size during use of the apparatus, causing a fluctuation in a pressure which is measures by said pressure detecting means.

9. **(Newly Added)** An apparatus according to claim 7, wherein said gas holes increase in size during use of the apparatus, causing a difference between a pressure